

## IN THE CLAIMS

**Claim 1 (currently amended).** An adhesive sheet ~~composed~~ formed of a blend of a rubber S1 and a thermoplastic ~~T2~~,

- a) the blend being microphase-separated, and  
the blend possessing
- b) ~~the blend possessing~~ at least two softening temperatures, at least one softening temperature being greater than 65°C and less than 125°C,
- c) a G' at 23°C, as measured by test method A, of greater than  $10^7$  Pas,
- d) a G" at 23°C, as measured by test method A, of greater than  $10^6$  Pas,
- e) and a crossover, as measured by test method A, of less than 125°C.

**Claim 2 (currently amended).** The adhesive sheet of claim 1, ~~characterized in that~~  
wherein the rubber is a synthetic rubber.

**Claim 3 (currently amended).** The adhesive sheet of claim 2, ~~characterized in that~~  
wherein said synthetic rubbers rubber S1 used are is selected from the group  
consisting of polyvinyl butyral, polyvinyl formal, nitrile rubbers, nitrile-butadiene rubbers, hydrogenated nitrile-butadiene rubbers, polyacrylate rubbers, chloroprene rubbers, ethylene-propylene-diene rubbers, methyl-vinyl-silicone rubbers, fluorosilicone rubbers, tetrafluoroethylene-propylene copolymer rubbers, butyl rubbers, and styrene-butadiene rubbers.

**Claim 4 (currently amended).** The adhesive sheet of claim 3, ~~characterized in that the~~  
wherein said synthetic rubber is a nitrile rubber.

**Claim 5 (currently amended).** The adhesive sheet of claim 4, ~~characterized in that~~  
wherein

- a) the nitrile rubber possesses a softening temperature of -80°C to 0°C
- b) the thermoplastic possesses a softening temperature of 65°C to 125°C
- c) the nitrile rubber is insoluble in the thermoplastic.

**Claim 6 (currently amended).** The adhesive sheet of ~~at least one of the preceding~~  
~~claims, characterized in that~~ claim 1, wherein said adhesive sheet is the layer

~~thickness is between 10 and 100 µm thick, with particular preference between 30 and 80 µm.~~

Claim 7 (currently amended). The adhesive sheet of ~~at least one of the preceding claims, characterized in that the thermoplastics T2 are particularly preferably claim 1, wherein the thermoplastic T2 is~~ selected from the ~~groups group~~ consisting of copolyamides, polyethyl-vinyl acetates, polyvinyl acetates, polyolefins, polyurethanes, and copolymers.

Claim 8 (cancelled).

Claim 9 (currently amended). The adhesive sheet of ~~at least one of the preceding claims, characterized in that reactive resins used additionally comprise claim 1, wherein, in addition to said rubber S1 and said thermoplastic T2, said blend further comprises a reactive resin selected from the group consisting of epoxy resins, and/or phenolic resins, and/or novolak resins and combinations thereof.~~

Claim 10 (currently amended). ~~The use of an adhesive sheet of at least one of the preceding claims A method for bonding polyimide-, polyester- or epoxy-based chip modules and on PVC, ABS, PET, PC, PP or PE card bodies which comprises bonding said chip modules on said card bodies with the adhesive sheet of claim 1.~~

Claim 11 (currently amended). A method for producing a heat-activatable adhesive tape, ~~characterized in that an adhesive sheet of claims 1 to 9 is coated which comprises coating the adhesive sheet of claim 1 onto a release paper or a release film.~~

Claim 12 (currently amended). The method of claim 11, ~~characterized in that the heat-activatable wherein said adhesive tape is die-cut.~~

Claim 13. ~~The method of at least one of claims 11 and 12, characterized in that the heat-activatable adhesive tape is processed with A method for implanting a chip module in a card body, which comprises implanting said chip module in said card body with a heat activatable adhesive tape comprised of the adhesive sheet of claim 1 coated onto a release paper or release film, and~~

**an implanter having an implanting die at an implanting die temperature of 150°C.**

Claim 14 (new).      The adhesive sheet of claim 6, wherein said thickness is between 30 and 80  $\mu\text{m}$ .